

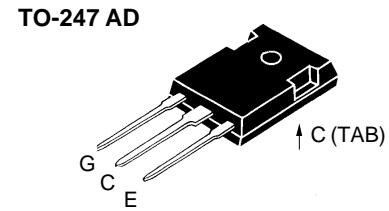
HiPerFAST™ IGBT

IXGH 40N30
IXGH 40N30A
IXGH 40N30B

V_{CES}	I_{C25}	V_{CE(sat)}	t_{fi}
600 V	60 A	1.8 V	220ns
600 V	60 A	2.1 V	120ns
600 V	60 A	2.4 V	75 ns

Preliminary data

Symbol	Test Conditions	Maximum Ratings	
V _{CES}	T _J = 25°C to 150°C	300	V
V _{CGR}	T _J = 25°C to 150°C; R _{GE} = 1 MΩ	300	V
V _{GES}	Continuous	±20	V
V _{GEM}	Transient	±30	V
I _{C25}	T _c = 25°C	60	A
I _{C90}	T _c = 90°C	40	A
I _{CM}	T _c = 25°C, 1 ms	160	A
SSOA (RBSOA)	V _{GE} = 15 V, T _{VJ} = 125°C, R _G = 10 Ω Clamped inductive load, L = 30 μH	I _{CM} = 80 @ 0.8 V _{CES}	A
P _c	T _c = 25°C	200	W
T _J		-55 ... +150	°C
T _{JM}		150	°C
T _{stg}		-55 ... +150	°C
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	°C
M _d	Mounting torque (M3)	1.13/10	Nm/lb.in.
Weight	TO-247 AD	6	g



G = Gate,
E = Emitter,
C = Collector,
TAB = Collector

Features

- International standard package JEDEC TO-247 AD
- High current handling capability
- Newest generation HDMOS™ process
- MOS Gate turn-on - drive simplicity

Applications

- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switched-mode and resonant-mode power supplies

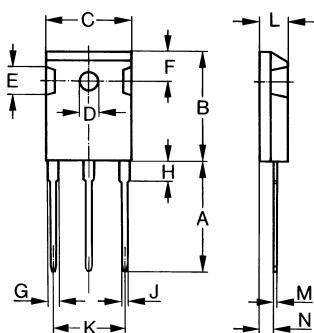
Advantages

- High power density
- Suitable for surface mounting
- Switching speed for high frequency applications
- Easy to mount with 1 screw, (isolated mounting screw hole)

Symbol	Test Conditions	Characteristic Values		
		(T _J = 25°C, unless otherwise specified)	min.	typ.
BV _{CES}	I _C = 250 μA, V _{GE} = 0 V	300		V
V _{GE(th)}	I _C = 250 μA, V _{CE} = V _{GE}	2.5		5 V
I _{CES}	V _{CE} = 0.8 • V _{CES} V _{GE} = 0 V	T _J = 25°C T _J = 125°C		200 μA 1 mA
I _{GES}	V _{CE} = 0 V, V _{GE} = ±20 V			±100 nA
V _{CE(sat)}	I _C = I _{C90} , V _{GE} = 15 V	40N30 40N30A 40N30B		1.8 V 2.1 V 2.4 V

Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
g_{fs}	$I_C = I_{C90}$; $V_{CE} = 10 \text{ V}$, Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $\leq 2\%$	20	28	S
C_{ies} C_{oes} C_{res}	$V_{CE} = 25 \text{ V}$, $V_{GE} = 0 \text{ V}$, $f = 1 \text{ MHz}$	2500	pF	
		210	pF	
		60	pF	
Q_g Q_{ge} Q_{gc}	$I_C = I_{C90}$, $V_{GE} = 15 \text{ V}$, $V_{CE} = 0.5 V_{CES}$	145	170	nC
		23	35	nC
		50	75	nC
$t_{d(on)}$ t_{ri} $t_{d(off)}$ t_{fi} E_{off}	Inductive load, $T_J = 25^\circ\text{C}$ $I_C = I_{C90}$, $V_{GE} = 15 \text{ V}$, $L = 100 \mu\text{H}$, $V_{CE} = 0.8 V_{CES}$, $R_G = R_{off} = 1.0 \Omega$ Switching times may increase for V_{CE} (Clamp) $> 0.8 \cdot V_{CES}$, higher T_J or increased R_G	25	ns	
		40	ns	
		170	ns	
		40N30	100	ns
		40N30A	75	ns
		40N30B	230	ns
		40N30	120	ns
		40N30A	75	ns
		40N30B	1.6	mJ
$t_{d(on)}$ t_{ri} E_{on} $t_{d(off)}$ t_{fi} E_{off}	Inductive load, $T_J = 125^\circ\text{C}$ $I_C = I_{C90}$, $V_{GE} = 15 \text{ V}$, $L = 100 \mu\text{H}$ $V_{CE} = 0.8 V_{CES}$, $R_G = R_{off} = 1.0 \Omega$ Switching times may increase for V_{CE} (Clamp) $> 0.8 \cdot V_{CES}$, higher T_J or increased R_G	25	ns	
		40	ns	
		0.3	mJ	
		40N30	250	ns
		40N30A	150	ns
		40N30B	90	ns
		40N30	350	ns
		40N30A	220	ns
		40N30B	130	ns
R_{thJC} R_{thCK}			0.62	K/W
			0.25	K/W

TO-247 AD (IXGH) Outline



Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102